



**SGS-THOMSON**  
MICROELECTRONICS

**SM15T6V8, A → 220, A**

**SM15T6V8C, A → 200C, A**

## UNI-AND BIDIRECTIONAL TRANSIENT VOLTAGE SUPPRESSORS

- HIGH SURGE CAPABILITY :  
1.5 kW / 1 ms EXPO
- VERY FAST CLAMPING TIME :  
1 ps FOR UNIDIRECTIONAL TYPES  
5 ns FOR BIDIRECTIONAL TYPES
- LARGE VOLTAGE RANGE :  
5.5 V → 188 V
- ORDER CODE :  
TYPE NUMBER FOR UNIDIRECTIONAL TYPES, TYPE NUMBER + SUFFIX C FOR BIDIRECTIONAL TYPES



### DESCRIPTION

Transient voltage suppressor diodes especially useful in protecting integrated circuits, MOS, hybrids and other voltage-sensitive semiconductors and components.

### SURFACE MOUNT TRANSIL FEATURES

- A PERFECT PICK AND PLACE BEHAVIOUR
- AN EXCELLENT ON BOARD STABILITY
- A FULL COMPATIBILITY WITH BOTH GLUING AND PASTE SOLDERING TECHNOLOGIES
- BODY MARKED WITH TYPE CODE AND LOGO
- STANDARD PACKAGING : 12 mm TAPE (EIA STD. RS481)
- TINNED COPPER LEADS
- HIGH TEMPERATURE RESISTANT RESIN

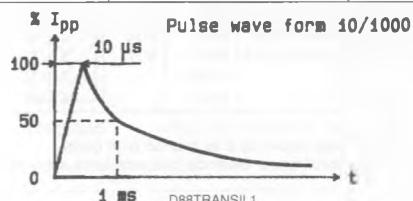
### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
P <sub>p</sub>	Peak Pulse Power for 1 ms Exponential Pulse	T <sub>j</sub> Initial = 25 °C See note 1	1500 W
P	Power Dissipation on Infinite Heatsink	T <sub>amb</sub> = 25 °C	1.7 W
I <sub>FSM</sub>	Non Repetitive Surge Peak Forward Current for Unidirectional Types	T <sub>j</sub> Initial = 25 °C t = 10 ms	150 A
T <sub>stg</sub> T <sub>j</sub>	Storage and Operating Junction Temperature Range	- 65 to 175 150 °C	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering During 10 s	260 °C	°C

### THERMAL RESISTANCE

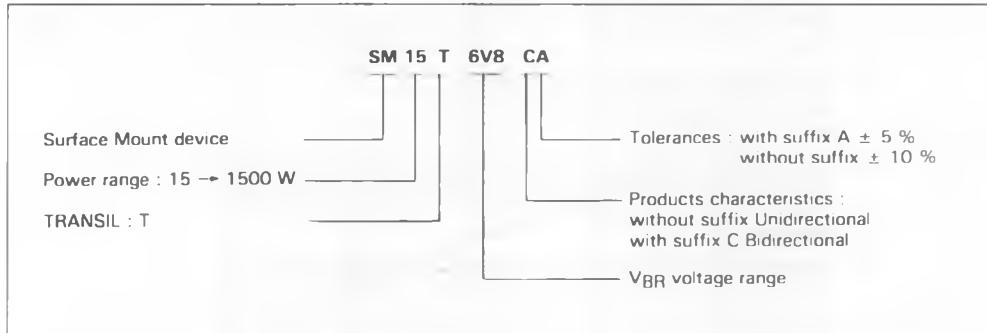
Symbol	Parameter	Value	Unit
R <sub>th(j-l)</sub>	Junction-leads	10 °C/W	

Note : 1. For surges upper than the maximum values, the diode will present a short-circuit anode-cathode.



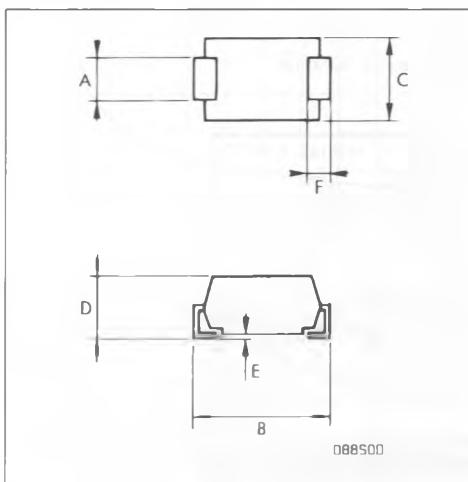


## ORDER CODE



## PACKAGE MECHANICAL DATA

SOD 15 Plastic

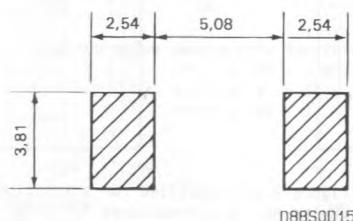


Ref.	Millimetres		Inches	
	Min.	Max.	Min.	Max.
A	2.8	3.2	0.110	0.126
B	7.6	8.0	0.300	0.315
C	4.8	5.2	0.190	0.200
D	2.5	3.1	0.098	0.122
E	—	0.1	—	0.004
F	1.3	1.7	0.051	0.067

Laser marking.

The logo indicates cathode for unidirectional types.

## FOOT PRINT DIMENSIONS (Millimeters)



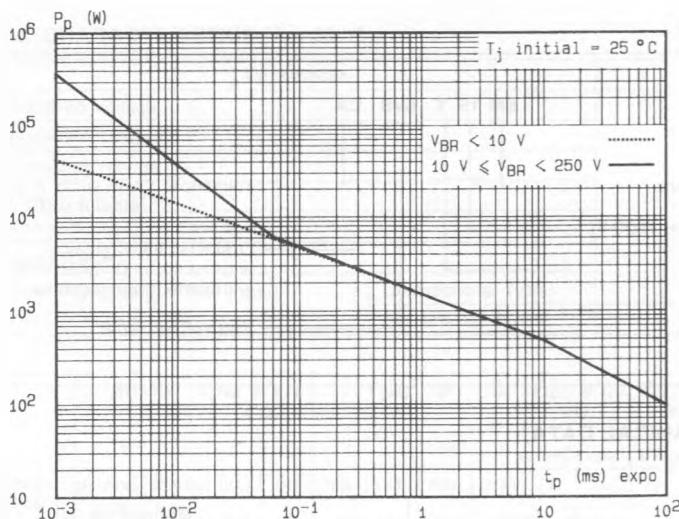


Fig.1 - Peak pulse power versus exponential pulse duration.

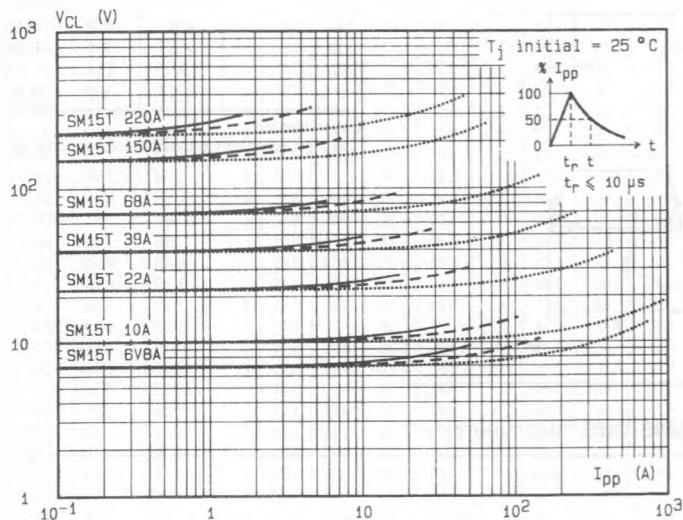


Fig.2 - Clamping voltage versus peak pulse current.

exponential waveform  $t = 20 \mu s$  .....  
 $t = 1 ms$  ---  
 $t = 10 ms$  —

Note : The curves of the figure 2 are specified for a junction temperature of 25 °C before surge. The given results may be extrapolated for other junction temperatures by using the following formula :  $\Delta V(BR) = \alpha T(V(BR)) \times [T_j - 25] \times V(BR)$   
 For intermediate voltages, extrapolate the given results.

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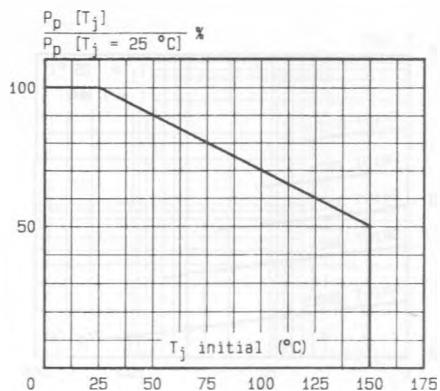


Fig.3 - Allowable power dissipation versus junction temperature.

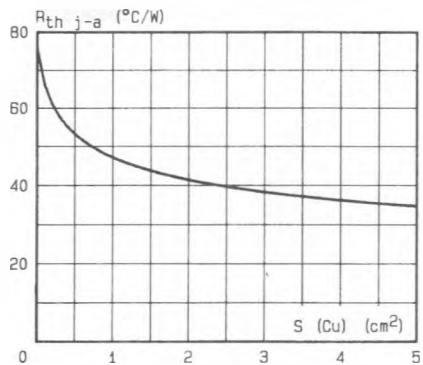


Fig.5 - Thermal resistance junction-ambient versus Cu surface (printed circuit).

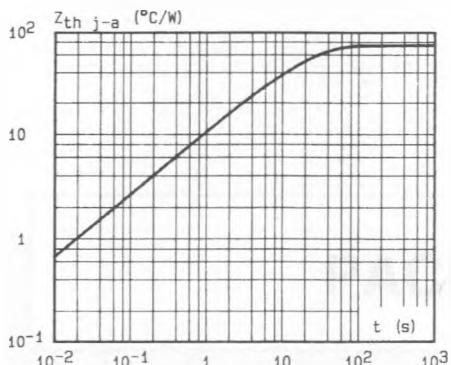


Fig.6 - Transient thermal impedance junction-ambient versus pulse duration.

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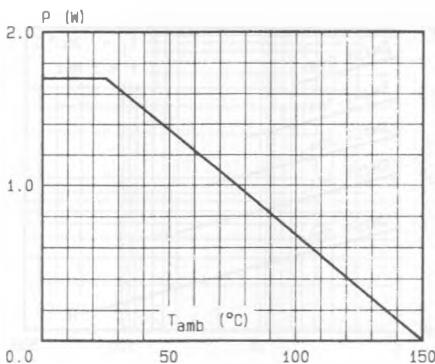


Fig.4 - Power dissipation versus ambient temperature.

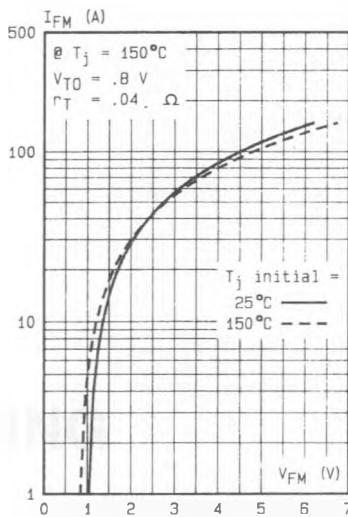


Fig.7 - Peak forward current versus peak forward voltage drop (typical values for unidirectional types).

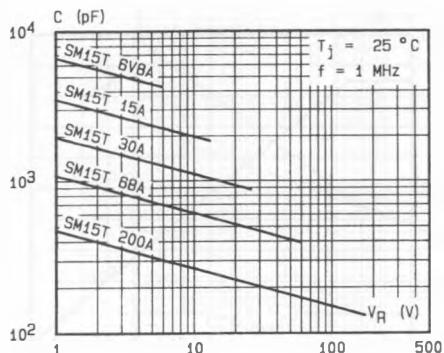


Fig.8a - Capacitance versus reverse applied voltage for unidirectional types (typical values).

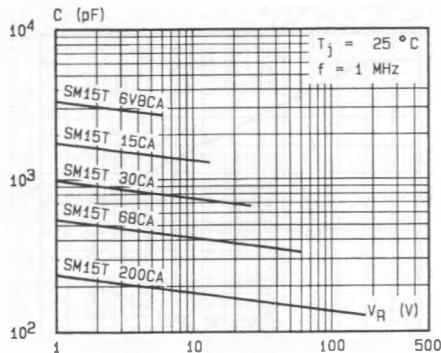


Fig.8b - Capacitance versus reverse applied voltage for bidirectional types (typical values).

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